

MOSFET – N-Channel, POWERTRENCH®

150 V, 4.1 A, 66 mΩ

FDS2582

Features

- $R_{DS(on)} = 57 \text{ m}\Omega$ (Typ.), $V_{GS} = 10 \text{ V}$, $I_D = 4.1 \text{ A}$
- $Q_{g(TOT)} = 19 \text{ nC}$ (Typ.), $V_{GS} = 10 \text{ V}$
- Low Miller Charge
- Low Q_{RR} Body Diode
- Optimized Efficiency at High Frequencies
- UIS Capability (Single Pulse and Repetitive Pulse)
- This Device is Pb-Free and Halide free

Applications

- DC/DC Converters and Off-Line UPS
- Distributed Power Architectures and VRMs
- Primary Switch for 24 V and 48 V Systems
- High Voltage Synchronous Rectifier
- Direct Injection / Diesel Injection Systems
- 42 V Automotive Load Control
- Electronic Valve Train Systems

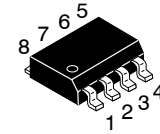
MOSFET MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter		Ratings	Unit
V_{DS}	Drain to Source Voltage		150	V
V_{GS}	Gate to Source Voltage		± 20	V
I_D	Drain Current	Continuous ($T_A = 25^\circ\text{C}$, $V_{GS} = 10 \text{ V}$, $R_{\theta JA} = 50^\circ\text{C/W}$)	4.1	A
		Continuous ($T_A = 100^\circ\text{C}$, $V_{GS} = 10 \text{ V}$, $R_{\theta JA} = 50^\circ\text{C/W}$)	2.6	A
		Pulsed	Figure 4	A
E_{AS}	Single Pulse Avalanche Energy (Note 1)		252	mJ
P_D	Power Dissipation		2.5	W
	Derate above 25°C		20	mW/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature		-55 to 150	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

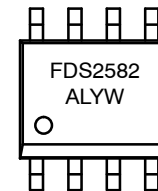
1. Starting $T_J = 25^\circ\text{C}$, $L = 56 \text{ mH}$, $I_{AS} = 3 \text{ A}$.

V_{DS} MAX	$R_{DS(on)}$ MAX	I_D MAX
150 V	66 mΩ @ 10 V	4.1 A



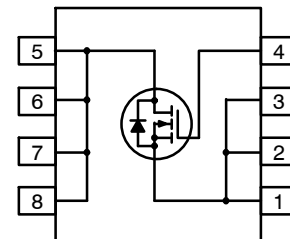
SOIC8
(SO-8)
CASE 751EB

MARKING DIAGRAM



FDS2582 = Device Code
A = Assembly Site
L = Wafer Lot Number
YW = Assembly Start Week

PIN CONNECTIONS



ORDERING INFORMATION

See detailed ordering and shipping information on page 13 of this data sheet.

THERMAL CHARACTERISTICS

Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient at 10 seconds (Note 3)	50	$^{\circ}\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient at 1000 seconds (Note 3)	80	$^{\circ}\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance, Junction to Case (Note 2)	25	$^{\circ}\text{C}/\text{W}$

2. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design.

3. $R_{\theta JA}$ is measured with 1.0 in² copper on FR-4 board.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

B_{VDSS}	Drain to Source Breakdown Voltage	$I_D = 250\ \mu\text{A}$, $V_{GS} = 0\ \text{V}$	150	–	–	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 120\ \text{V}$, $V_{GS} = 0\ \text{V}$	–	–	1	μA
		$V_{DS} = 120\ \text{V}$, $V_{GS} = 0\ \text{V}$, $T_C = 150^{\circ}\text{C}$	–	–	250	
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20\ \text{V}$	–	–	± 100	nA

ON CHARACTERISTICS

$V_{GS(TH)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 250\ \mu\text{A}$	2	–	4	V
$R_{DS(on)}$	Drain to Source On Resistance	$I_D = 4.1\ \text{A}$, $V_{GS} = 10\ \text{V}$	–	57	66	$\text{m}\Omega$
		$I_D = 2\ \text{A}$, $V_{GS} = 6\ \text{V}$	–	65	98	
		$I_D = 4.1\ \text{A}$, $V_{GS} = 10\ \text{V}$, $T_C = 150^{\circ}\text{C}$	–	125	146	

DYNAMIC CHARACTERISTICS

C_{ISS}	Input Capacitance	$V_{DS} = 25\ \text{V}$, $V_{GS} = 0\ \text{V}$, $f = 1\ \text{MHz}$	–	1290	–	pF
C_{OSS}	Output Capacitance		–	150	–	pF
C_{RSS}	Reverse Transfer Capacitance		–	32	–	pF
$Q_{g(TOT)}$	Total Gate Charge at 10 V	$V_{GS} = 0\ \text{V}$ to 10 V, $V_{DD} = 75\ \text{V}$, $I_D = 4.1\ \text{A}$, $I_g = 1.0\ \text{mA}$	–	19	25	nC
$Q_{g(TH)}$	Threshold Gate Charge	$V_{GS} = 0\ \text{V}$ to 2 V, $V_{DD} = 75\ \text{V}$, $I_D = 4.1\ \text{A}$, $I_g = 1.0\ \text{mA}$	–	2.3	3.0	nC
Q_{gs}	Gate to Source Gate Charge	$V_{DD} = 75\ \text{V}$, $I_D = 4.1\ \text{A}$, $I_g = 1.0\ \text{mA}$	–	5.4	–	nC
Q_{gs2}	Gate Charge Threshold to Plateau		–	3.1	–	nC
Q_{gd}	Gate to Drain "Miller" Charge		–	4.4	–	nC

RESISTIVE SWITCHING CHARACTERISTICS ($V_{GS} = 10\ \text{V}$)

t_{ON}	Turn-On Time	$V_{DD} = 75\ \text{V}$, $I_D = 4.1\ \text{A}$, $V_{GS} = 10\ \text{V}$, $R_{GS} = 16\ \Omega$	–	–	45	ns
$t_{d(ON)}$	Turn-On Delay Time		–	11	–	ns
t_r	Rise Time		–	19	–	ns
$t_{d(OFF)}$	Turn-Off Delay Time		–	36	–	ns
t_f	Fall Time		–	26	–	ns
t_{OFF}	Turn-Off Time		–	–	92	ns

DRAIN-SOURCE DIODE CHARACTERISTICS

V_{SD}	Source to Drain Diode Voltage	$I_{SD} = 4.1\ \text{A}$	–	–	1.25	V
		$I_{SD} = 2\ \text{A}$	–	–	1.0	V
t_{rr}	Reverse Recovery Time	$I_{SD} = 4.1\ \text{A}$, $dI_{SD}/dt = 100\ \text{A}/\mu\text{s}$	–	–	63	ns
Q_{RR}	Reverse Recovered Charge	$I_{SD} = 4.1\ \text{A}$, $dI_{SD}/dt = 100\ \text{A}/\mu\text{s}$	–	–	116	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

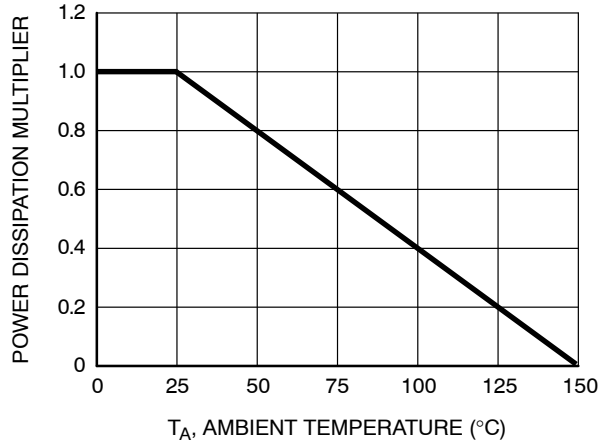
(T_A = 25°C unless otherwise noted)

Figure 1. Normalized Power Dissipation vs. Ambient Temperature

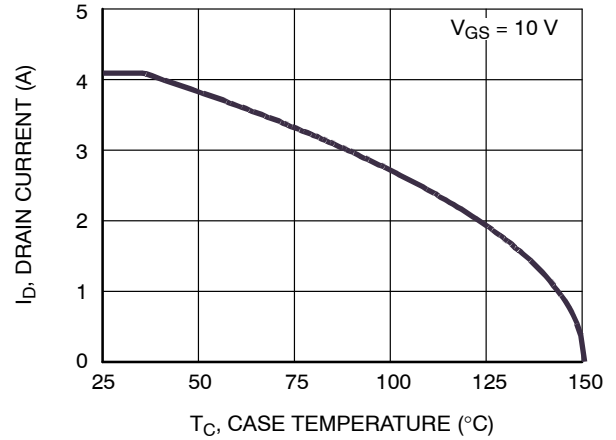


Figure 2. Maximum Continuous Drain Current vs. Case Temperature

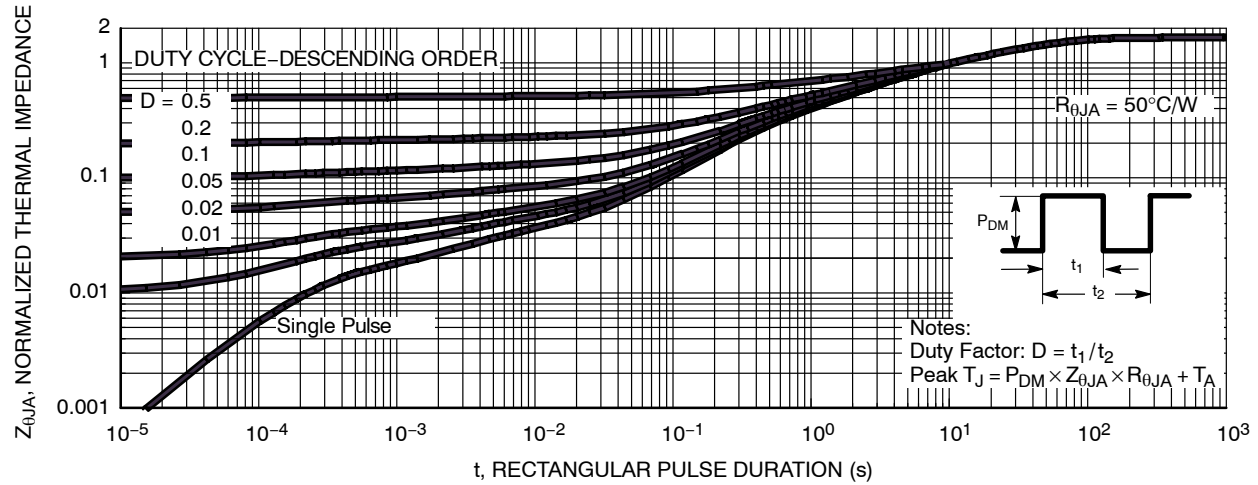


Figure 3. Normalized Maximum Transient Thermal Impedance

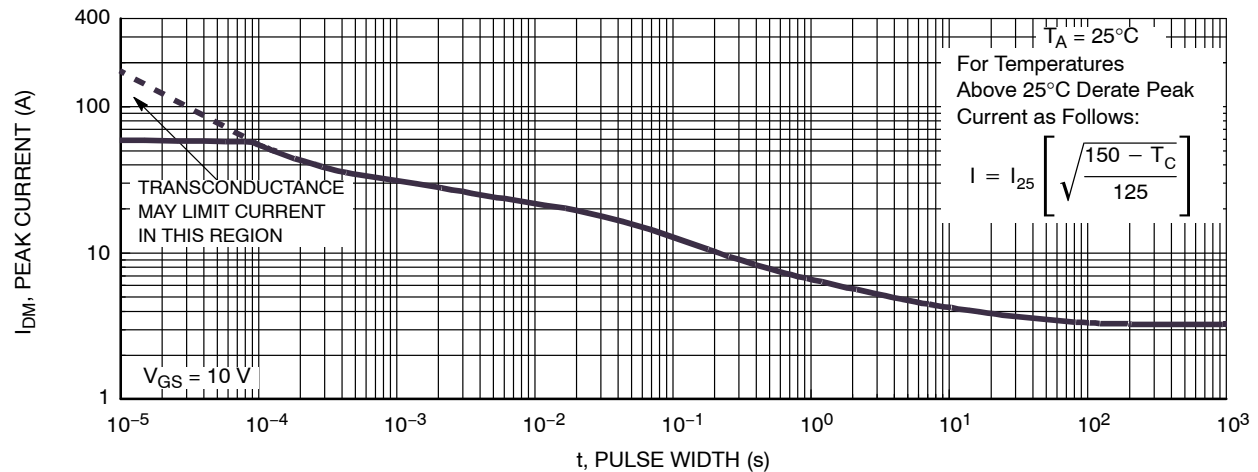


Figure 4. Peak Current Capability

TYPICAL CHARACTERISTICS

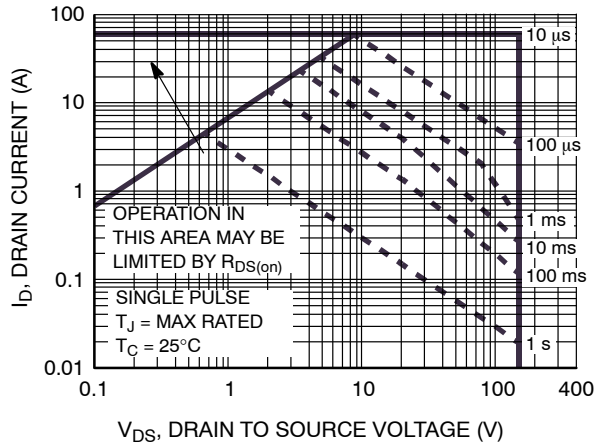
(T_A = 25°C unless otherwise noted) (continued)

Figure 5. Forward Bias Safe Operating Area

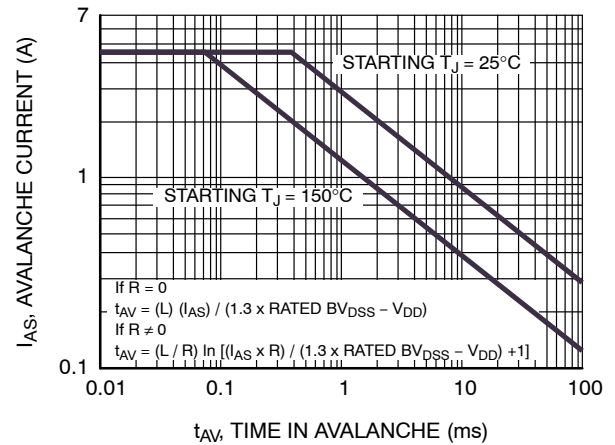
NOTE: Refer to onsemi Application Notes [AN-7514](#) and [AN-7515](#)

Figure 6. Unclamped Inductive Switching Capability

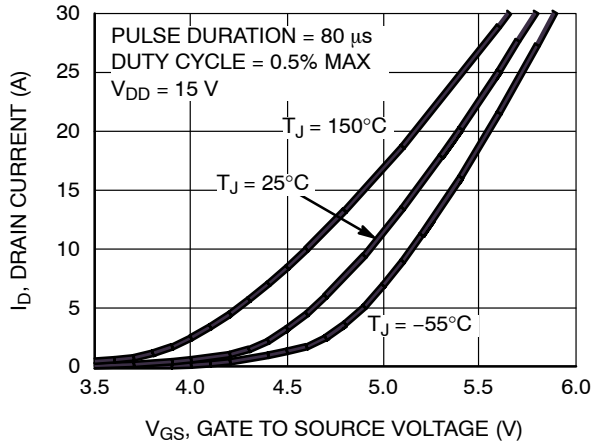


Figure 7. Transfer Characteristics

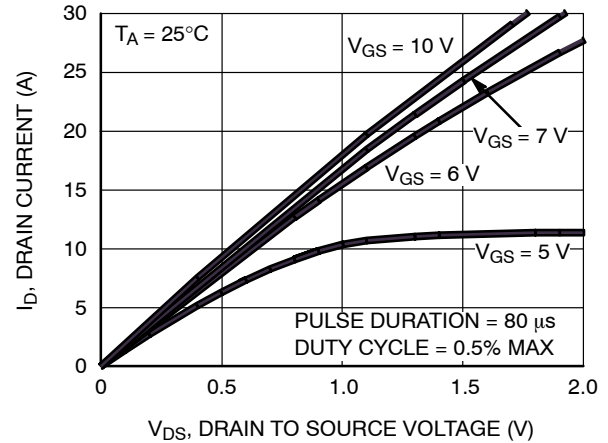


Figure 8. Saturation Characteristics

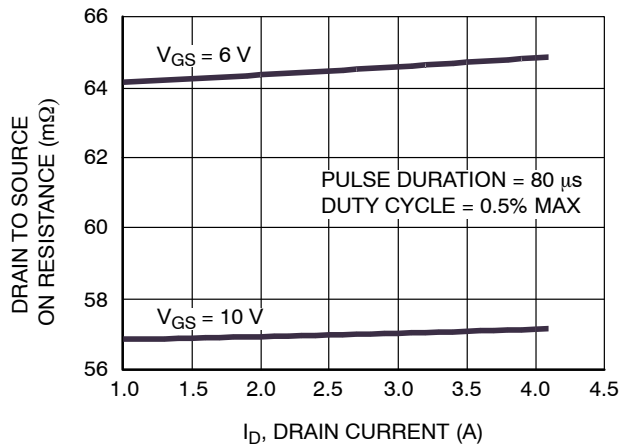


Figure 9. Drain to Source On Resistance vs. Drain Current

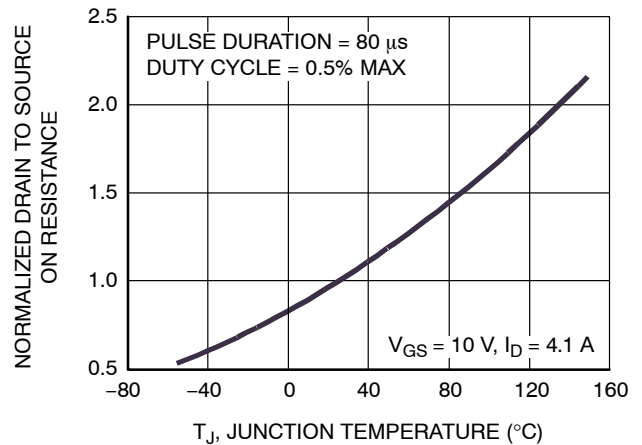


Figure 10. Normalized Drain to Source On Resistance vs. Junction Temperature

TYPICAL CHARACTERISTICS

($T_A = 25^\circ\text{C}$ unless otherwise noted) (continued)

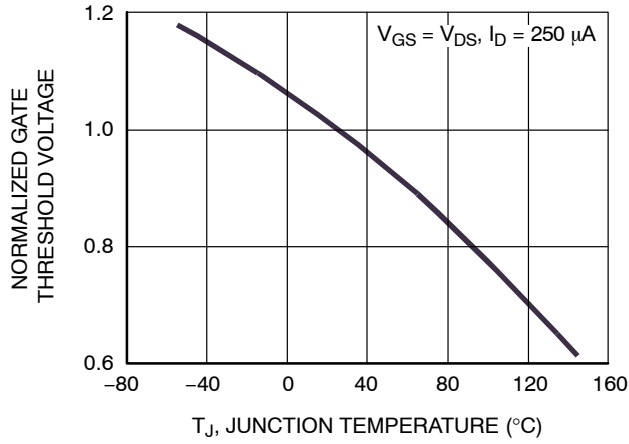


Figure 11. Normalized Gate Threshold Voltage vs. Junction Temperature

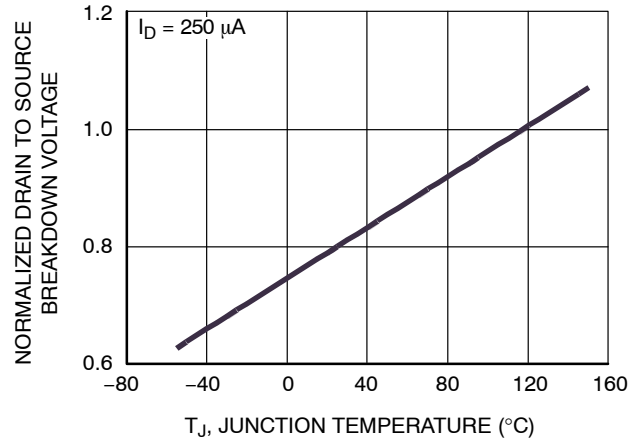


Figure 12. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature

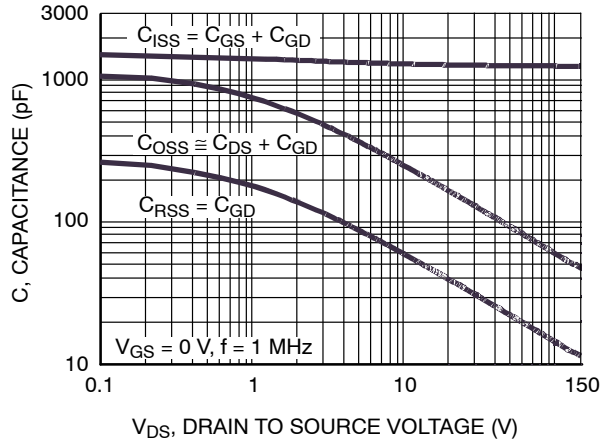


Figure 13. Capacitance vs. Drain to Source Voltage

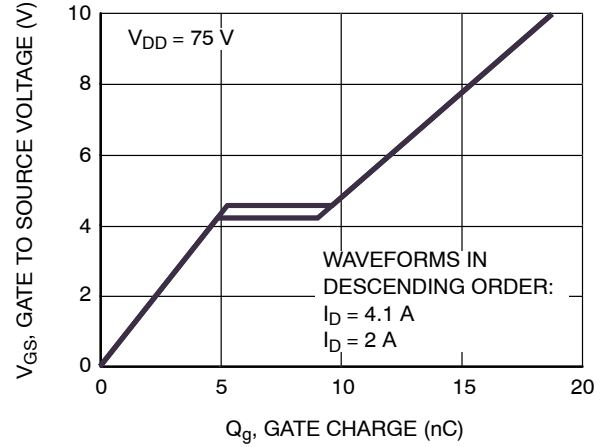


Figure 14. Gate Charge Waveforms for Constant Gate Currents

TEST CIRCUITS AND WAVEFORMS

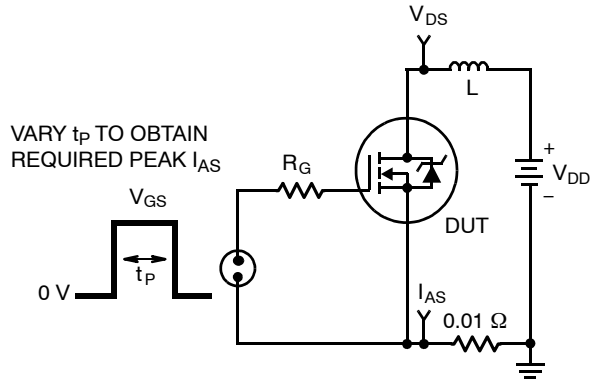


Figure 15. Unclamped Energy Test Circuit

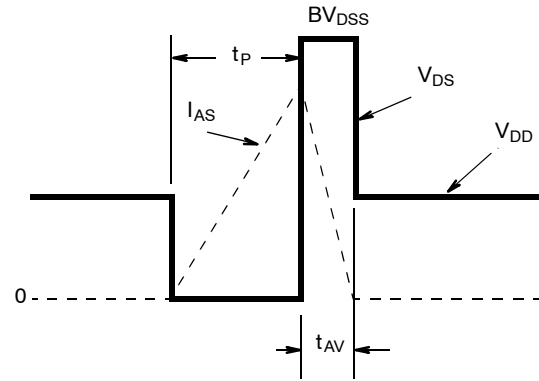


Figure 16. Unclamped Waveforms

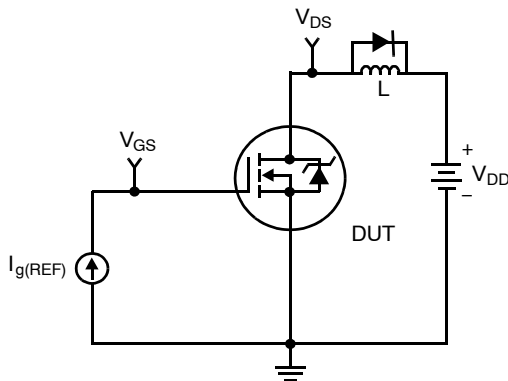


Figure 17. Gate Charge Test Circuit

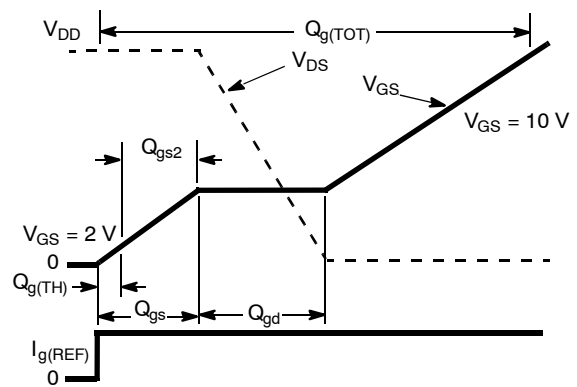


Figure 18. Gate Charge Waveforms

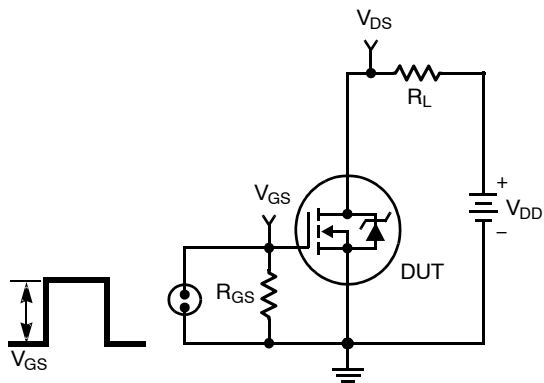


Figure 19. Switching Time Test Circuit

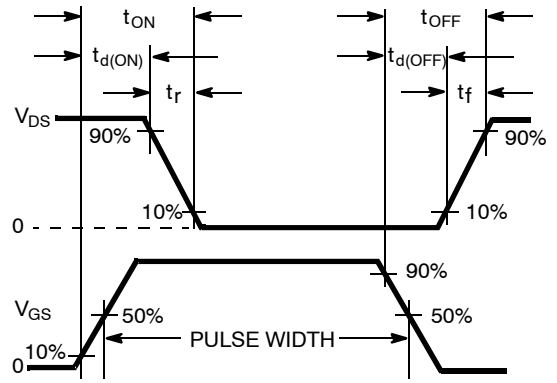


Figure 20. Switching Time Waveforms

THERMAL RESISTANCE VS. MOUNTING PAD AREA

The maximum rated junction temperature, T_{JM} , and the thermal resistance of the heat dissipating path determines the maximum allowable device power dissipation, P_{DM} , in an application. Therefore the application's ambient temperature, T_A ($^{\circ}\text{C}$), and thermal resistance $R_{\theta JA}$ ($^{\circ}\text{C}/\text{W}$) must be reviewed to ensure that T_{JM} is never exceeded. Equation 1 mathematically represents the relationship and serves as the basis for establishing the rating of the part.

$$P_{DM} = \frac{(T_{JM} - T_A)}{R_{\theta JA}} \quad (\text{eq. 1})$$

In using surface mount devices such as the SO8 package, the environment in which it is applied will have a significant influence on the part's current and maximum power dissipation ratings. Precise determination of P_{DM} is complex and influenced by many factors:

1. Mounting pad area onto which the device is attached and whether there is copper on one side or both sides of the board.
2. The number of copper layers and the thickness of the board.
3. The use of external heat sinks.
4. The use of thermal vias.
5. Air flow and board orientation.
6. For non steady state applications, the pulse width, the duty cycle and the transient thermal response of the part, the board and the environment they are in.

onsemi provides thermal information to assist the designer's preliminary application evaluation. Figure 21 defines the $R_{\theta JA}$ for the device as a function of the top copper (component side) area. This is for a horizontally positioned FR-4 board with 1 oz copper after 1000 seconds of steady state power with no air flow. This graph provides the necessary information for calculation of the steady state junction temperature or power dissipation. Pulse applications can be evaluated using the **onsemi** device Spice thermal model or manually utilizing the normalized maximum transient thermal impedance curve.

Thermal resistances corresponding to other copper areas can be obtained from Figure 21 or by calculation using Equation 2. The area, in square inches is the top copper area including the gate and source pads.

$$R_{\theta JA} = 64 + \frac{26}{0.23 + \text{Area}} \quad (\text{eq. 2})$$

The transient thermal impedance ($Z_{\theta JA}$) is also effected by varied top copper board area. Figure 22 shows the effect of copper pad area on single pulse transient thermal impedance. Each trace represents a copper pad area in square inches corresponding to the descending list in the graph. Spice and SABER thermal models are provided for each of the listed pad areas.

Copper pad area has no perceivable effect on transient thermal impedance for pulse widths less than 100 ms. For pulse widths less than 100 ms the transient thermal impedance is determined by the die and package. Therefore, C THERM1 through C THERM5 and R THERM1 through R THERM5 remain constant for each of the thermal models. A listing of the model component values is available in Table 1.

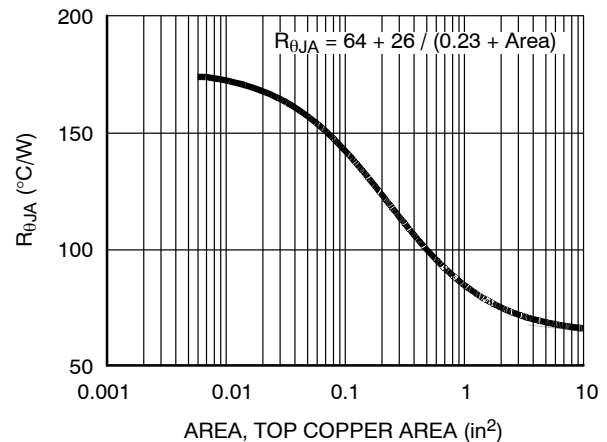


Figure 21. Thermal Resistance vs. Mounting Pad Area

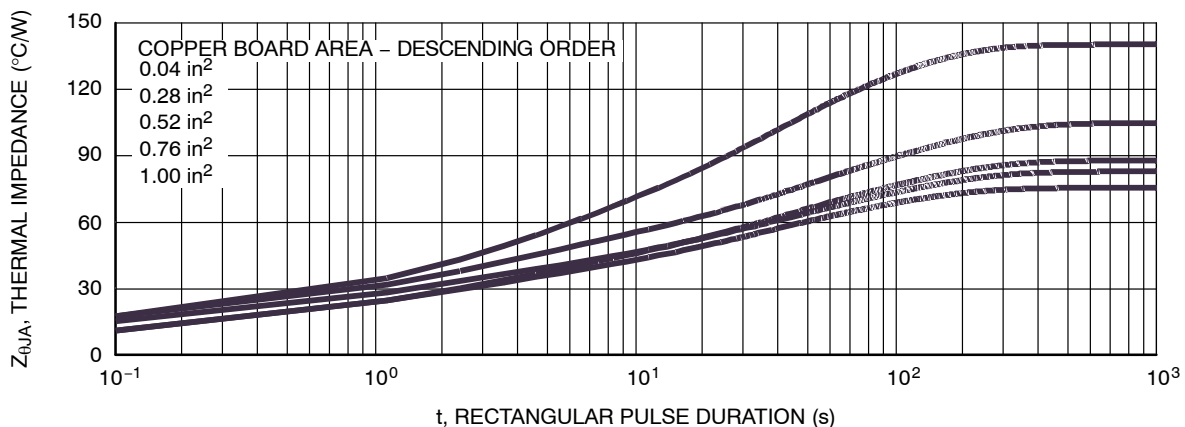


Figure 22. Thermal Impedance vs. Mounting Pad Area

PSPICE ELECTRICAL MODEL

```
.SUBCKT FDS2582 2 1 3;
```

rev July 2002

Ca 12 8 4.5e-10
Cb 15 14 5.0e-10
Cin 6 8 1.25e-9

Dbody 7 5 DbodyMOD
Dbreak 5 11 DbreakMOD
Dplcap 10 5 DplcapMOD

Ebreak 11 7 17 18 155.5
Eds 14 8 5 8 1
Egs 13 8 6 8 1
Esg 6 10 6 8 1
Evthres 6 21 19 8 1
Evtemp 20 6 18 22 1

It 8 17 1

Lgate 1 9 5.61e-9
Ldrain 2 5 1e-9
Lsource 3 7 1.98e-9

RLgate	1	9	56.1
RLdrain	2	5	10
RLsource	3	7	19.8

Mmed 16 6 8 8 MmedMOD
Mstro 16 6 8 8 MstroMOD
Mweak 16 21 8 8 MweakMOD

```
Rbreak 17 18 RbreakMOD 1
Rdrain 50 16 RdrainMOD 30.0e-3
Rgate 9 20 1.5
RSLC1 5 51 RSLCMOD 1e-6
RSLC2 5 50 1e3
Rsource 8 7 RsourceMOD 20.0e-3
Rvthres 22 8 RvthresMOD 1
Rvtemp 18 19 RvtempMOD 1
S1a 6 12 13 8 S1AMOD
S1b 13 12 13 8 S1BMOD
S2a 6 15 14 13 S2AMOD
S2b 13 15 14 13 S2BMOD
```

Vbat 22 19 DC 1

ESLC 51 50 VALUE={ (V(5,51)/ABS(V(5,51)))*(PWR(V(5,51)/(1e-6*60),2.5))}

.MODEL DbodyMOD D (IS=2.4E-12 N=1.0 RS=10.0e-3 TRS1=2.1e-3 TRS2=4.7e-7
+CJO=9.0e-10 M=0.64 TT=3.9e-8 XTI=4.6)
.MODEL DbreakMOD D (RS=1.0 TRS1=1.4e-3 TRS2=-5e-5)
.MODEL DplcapMOD D (CJO=2.8e-10 IS=1e-30 N=10 M=0.64)

```
.MODEL MmedMOD NMOS (VTO=3.5 KP=4.0 IS=1e-30 N=10 TOX=1 L=1u W=1u RG=1.5)
.MODEL MstroMOD NMOS (VTO=4.2 KP=50 IS=1e-30 N=10 TOX=1 L=1u W=1u)
.MODEL MweakMOD NMOS (VTO=2.92 KP=0.04 IS=1e-30 N=10 TOX=1 L=1u W=1u RG=15 RS=0.1)
```

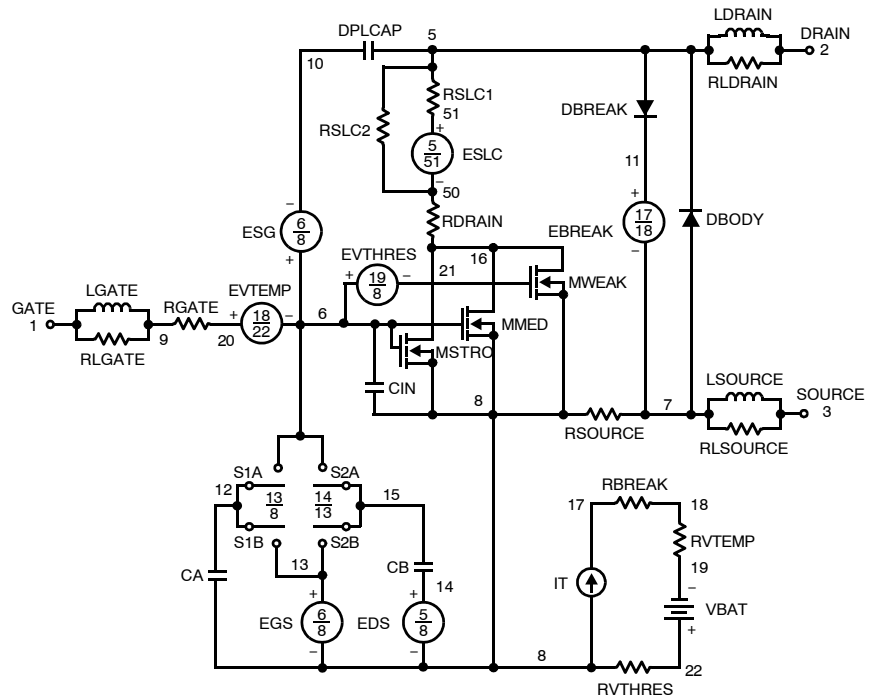


Figure 23.

FDS2582

```
.MODEL RbreakMOD RES (TC1=1.1e-3 TC2=-1.0e-8)
.MODEL RdrainMOD RES (TC1=1.15e-2 TC2=3.0e-5)
.MODEL RSLCMOD RES (TC1=4.4e-3 TC2=2.9e-6)
.MODEL RsourceMOD RES (TC1=1e-3 TC2=1e-6)
.MODEL RvthresMOD RES (TC1=-3.9e-3 TC2=-1.6e-5)
.MODEL RvtempMOD RES (TC1=-3.5e-3 TC2=1.5e-6)

.MODEL S1AMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-3.0 VOFF=-2.0)
.MODEL S1BMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-2.0 VOFF=-3.0)
.MODEL S2AMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-1.5 VOFF=1.0)
.MODEL S2BMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=1.0 VOFF=-1.5)

.ENDS
```

NOTE: For further discussion of the PSPICE model, consult **A New PSPICE Sub-Circuit for the Power MOSFET Featuring Global Temperature Options**; IEEE Power Electronics Specialist Conference Records, 1991, written by William J. Hepp and C. Frank Wheatley.

```
sw vcsp.s2b n13 n15 n14 n13 = model=s2bmod
```



10

FDS2582

```
v.vbat n22 n19 = dc=1
equations {
i (n51->n50) +=iscl
iscl: v(n51,n50) = ((v(n5,n51)/(1e-9+abs(v(n5,n51))))*((abs(v(n5,n51)*1e6/60))** 2.5))
}
}
```

SPICE THERMAL MODEL

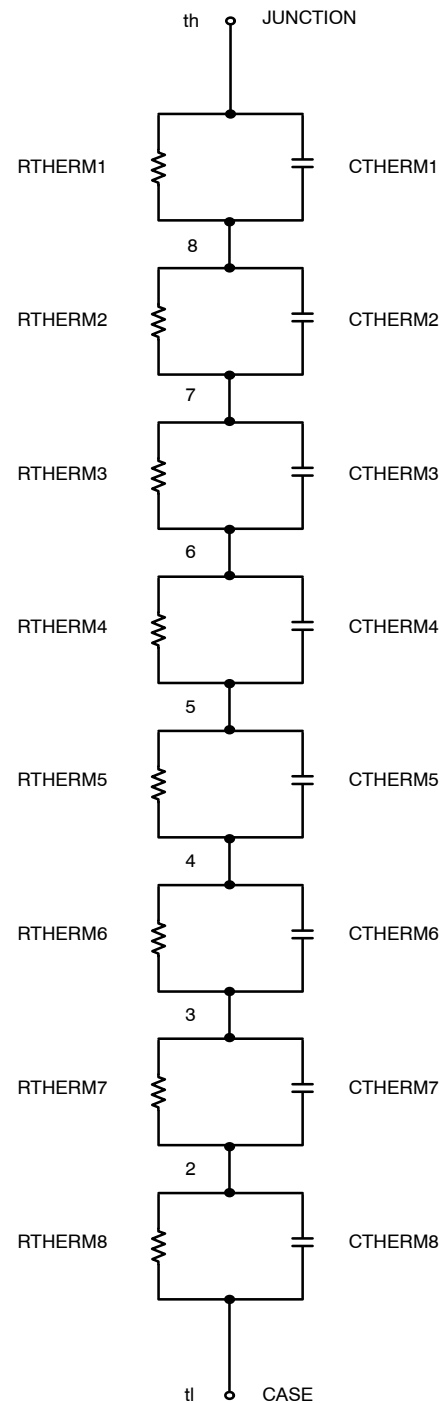
REV July 2002
 FDS2582
 Copper Area = 1.0 in²
 CTHERM1 TH 8 4e-4
 CTHERM2 8 7 5e-3
 CTHERM3 7 6 6e-2
 CTHERM4 6 5 9e-2
 CTHERM5 5 4 3e-1
 CTHERM6 4 3 4e-1
 CTHERM7 3 2 9e-1
 CTHERM8 2 TL 2

RTHERM1 TH 8 5e-1
 RTHERM2 8 7 6e-1
 RTHERM3 7 6 4
 RTHERM4 6 5 5
 RTHERM5 5 4 8
 RTHERM6 4 3 9
 RTHERM7 3 2 15
 RTHERM8 2 TL 23

SABER THERMAL MODEL

Copper Area = 1.0 in²
 template thermal_model th tl
 thermal_c th, tl
 {
 CTHERM1 TH 8 4e-4
 CTHERM2 8 7 5e-3
 CTHERM3 7 6 6e-2
 CTHERM4 6 5 9e-2
 CTHERM5 5 4 3e-1
 CTHERM6 4 3 4e-1
 CTHERM7 3 2 9e-1
 CTHERM8 2 TL 2

 RTHERM1 TH 8 5e-1
 RTHERM2 8 7 6e-1
 RTHERM3 7 6 4
 RTHERM4 6 5 5
 RTHERM5 5 4 8
 RTHERM6 4 3 9
 RTHERM7 3 2 15
 RTHERM8 2 TL 23
 }

**Figure 25.**

FDS2582

Table 1. THERMAL MODES

COMPONANT	0.04 in ²	0.28 in ²	0.52 in ²	0.76 in ²	1.0 in ²
CTHERM6	3.2e-1	3.5e-1	4.0e-1	4.0e-1	4.0e-1
CTHERM7	8.5e-1	9.0e-1	9.0e-1	9.0e-1	9.0e-1
CTHERM8	0.3	1.8	2.0	2.0	2.0
RTHERM6	24	18	12	10	9
RTHERM7	36	21	18	16	15
RTHERM8	53	37	30	28	23

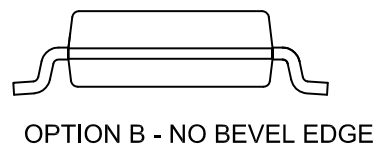
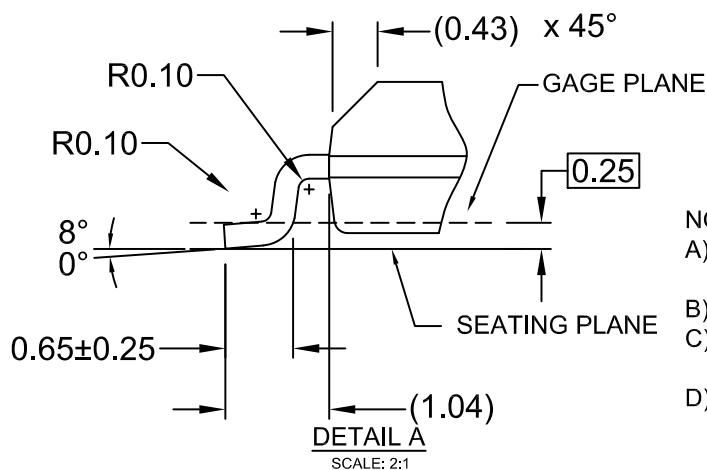
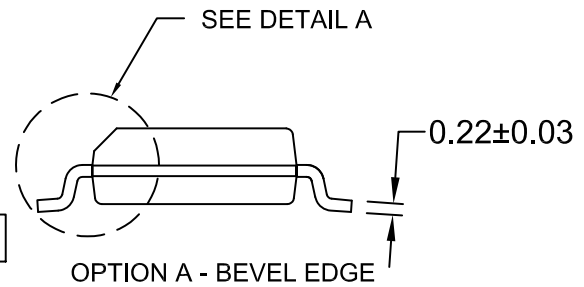
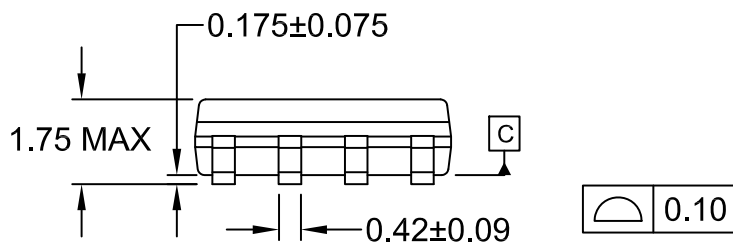
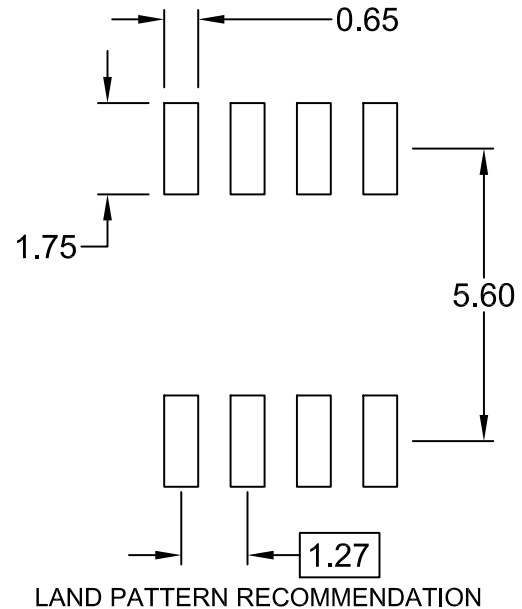
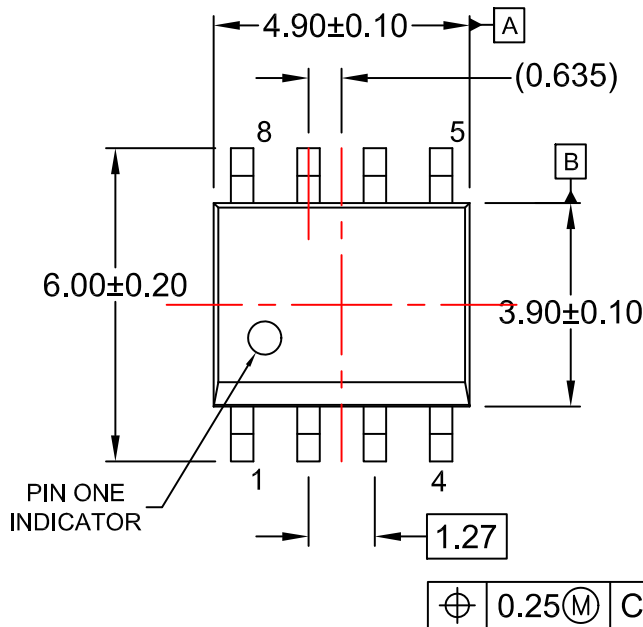
PACKAGE MARKING AND ORDERING INFORMATION

Device	Device Marking	Package Type	Reel Size	Tape Width	Shipping [†]
FDS2582	FDS2582	SOIC8 (SO-8) (Pb-Free)	330 mm	12 mm	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

SOIC8
CASE 751EB
ISSUE A

DATE 24 AUG 2017



NOTES:

- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AA.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- D) LANDPATTERN STANDARD: SOIC127P600X175-8M

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DESCRIPTION:	SOIC8	PAGE 1 OF 1

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